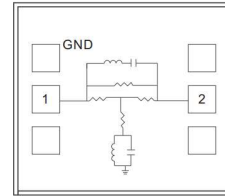


### Performance

- Frequency: 1~6GHz
- Insertion Loss:  $\leq 1.0\text{dB}$
- Attenuation: 3.0dB
- Impedance:  $50\Omega$
- Chip size:  $0.82 \times 0.8 \times 0.1\text{ mm}$

### Function Diagram

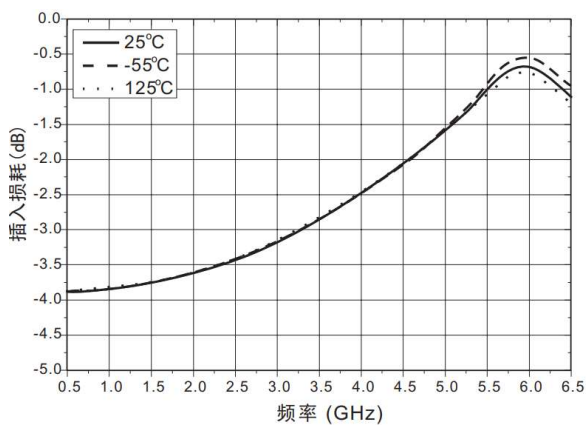


### Electrical Specifications (TA=+25°C, 50Ω system)

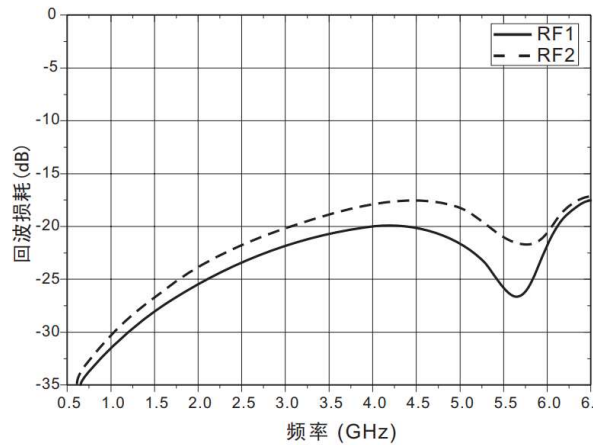
Parameter	Min	Typical	Max	Unit
Frequency Range		1.0~6.0		GHz
Insertion Loss	-	0.8	1.0	dB
Attenuation	-	3.0	-	dB
Input Return Loss	17	22	-	dB
Output Return Loss	15	20	-	dB

### Test Curves (Die chip test)

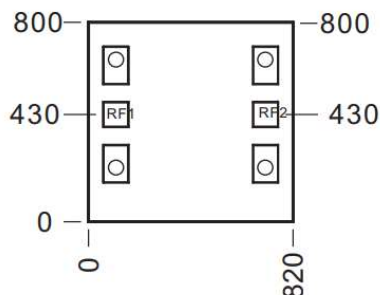
Insertion Loss



Return Loss



### Outline Size



### Note:

1. Unit:  $\mu\text{m}$
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated  
Pads size:  $100 \times 100\ \mu\text{m}$
5. Don't bonding on thru holes
6. Tolerance:  $\pm 50\ \mu\text{m}$

**Assembly Drawing**



**Bonding Pads Definition**

Number	Symbol	Description
RF1、RF2	RF Ports	RF ports, 50 ohm impedance
	GND	Bottom side of chip must be grounded

**Absolute Max. Ratings**

Static Protection Grade	Class 1A
Input Power	20 dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C



**ELECTROSTATIC SENSITIVE DEVICE**  
**OBSERVE HANDLING PRECAUTIONS**